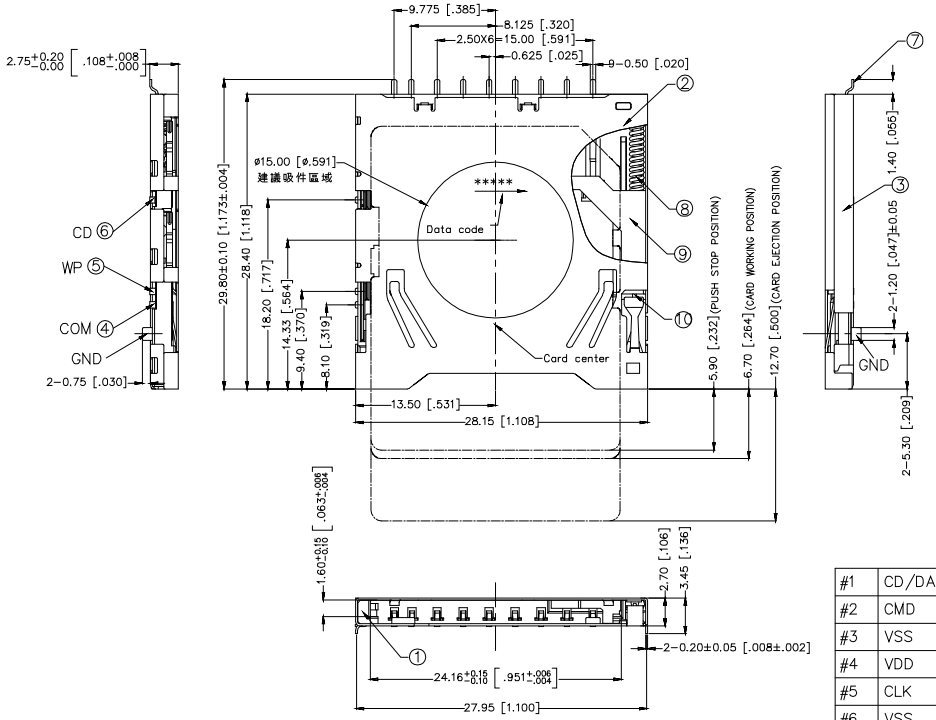
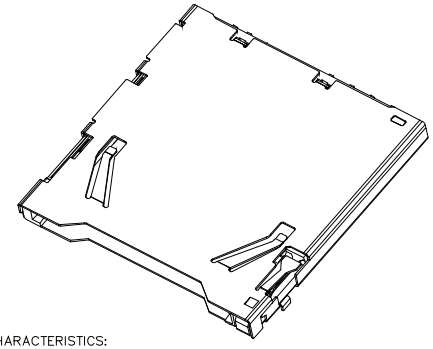
| 更改 REV | 更改內容 MODIFICATION |
|---|---|
| A | ECXXXXX |



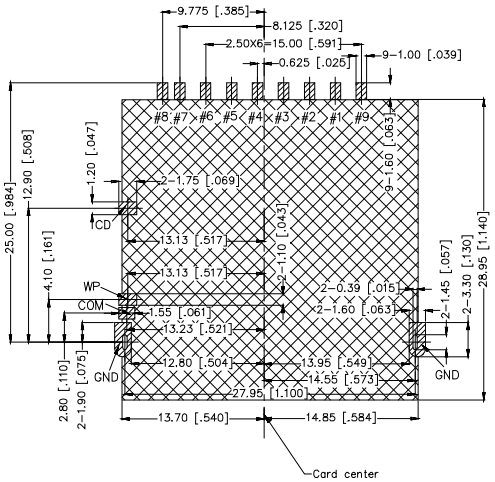



| | |
|---|---|
| #1 | CD/DAT3 |
| #2 | CMD |
| #3 | VSS |
| #4 | VDD |
| #5 | CLK |
| #6 | VSS |
| #7 | DAT0 |
| #8 | DATE1 |
| #9 | DATE2 |

SD SIGNAL PIN DEFINE

SPCIFICATION

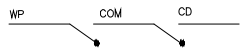
1. ELECTRICAL CHARACTERISTICS:
   1-1.CONTACT CURRENT RATING: 0.5A MAX.
   1-2.CONTACT RESISTANCE: 100 mOHMS MAX.
   1-3.OPERATING VOLTAGE: 3.3V.
   TESTING VOLTAGE: 500V AC 1 MINUTE.
   1-4.INSULATION RESISTANCE:
   INITIAL:1000 MOHMS MIN.
   AFTER TEST: 100 MOHMS MIN.
   1-5. OPERATING CURRENT: 0.1A MAX
2. MECHANICAL CHARACTERISTICS:
   2-1. TOTAL MATING FORCE: 40N MAX.
   2-3. DURABILITY : 10000 CYCLES.
3. ENVIRONMENT CHARACTERISTICS:
   3-1. OPERATING TEMPERATURE: -25°C~85°C
   3-2. STORAGE TEMPERATURE: -40°C~85°C
4. CARD OPERATION GUIDE:
   4-1. COMPATABLE CARD: SD&SDIO&MMC CARD
   4-2. CARD INSERT DIRECTION:
   THE CARD SIDE WITH ELECTRIC PAD SHOULD BE AGAINST TOP SHIELD
5. RECOMMENDED IR REFLOW PORCESS PEAK TEMPERATURE: 250±5°C, TIME 10s MAX .
6. ALL SMT CONTACTS AND PADS CO-PLANARITY: 0.10mm MAX
7. DON'T PERMIT TO BE PROCEEDED SMT RE-FLOW PROCESS WHEN PUSH-PUSH FEATURE IS IN WORKING POSITION




RECOMMENDED P.C.B. LAYOUT

PCB DIMENSION DEFAULT TOLERANCE: ±0.05

1. ▨ : RECOMMENDED SOLDER PAD AREA
2. ⊠ : TRACE KEEP OUT AREA




WP: WRITE PROTECT SWITCH CONTACT
COM: COMMON SWITCH CONTACT
CD: CARD DETECT SWITCH CONTACT

Switch Operation Diagram

| ELECTRIC FUNCTION | WRITE PROTECT SWITCH | | | | CARD DETECT SWITCH | |
|---|---|---|---|---|---|---|
| | WRITE UNABLE | | WRITE ENABLE | | | |
| CARD NAME | MMC | SD | MMC | SD | MMC | SD |
| WITHOUT CARD | | OPEN | | OPEN | OPEN | OPEN |
| CARD INSERTED | | OPEN | | CLOSE | CLOSE | CLOSE |
| SWITCH DIAGRAM | WP —— COM | | | | COM—— CD | |

| ITEM | DESCRIPTION | Q'TY | MATERIAL | FINISH | REMARK |
|---|---|---|---|---|---|
| 10 | CAM FOLLOWER | 1 | SUS304 | | |
| 9 | SLIDER | 1 | HTN | COLOR: BLACK | |
| 8 | SPRING | 1 | SWP | | |
| 7 | SIGNAL CONTACT | 9 | PH/BR | 50~100u" NI UNDERPLATING OVER ALL 100~200u" LEAD FREE TIN ALLOY PLATING AT SOLDERING AREA 30u" Min. AU OR 30u" Min Pd/Ni+3~5u"Au PLATING AT CONTACT AREA OR 1u" Min Au PLATING AT CONTACT AREA | |
| 6 | DETECT SWITCH CONTACT | 1 | PH/BR | 50~100u" NI UNDERPLATING OVER ALL 1u"Min Au PLATING AT SOLDERING AREA 1u"Min Au PLATING AT CONTACT AREA | |
| 5 | WRITE PROTECT SWITCH CONTACT | 1 | PH/BR | | |
| 4 | COMMON SWITCH CONTACT | 1 | PH/BR | | |
| 3 | BOTTOM SHELL | 1 | SUS304 | 30~100u"Min NI UNDERPLATING OVER ALL 1u"Min Au PLATING AT SOLDERING AREA | |
| 2 | TOP SHELL | 1 | SUS301 | CLEAN | |
| 1 | HOUSING | 1 | LCP | COLOR: BLACK | |

| GENERIAL TOLERANCE | |
|---|---|
| X.± 0.50 | X.°± 5 ° |
| .X± 0.30 | .X°± 2 ° |
| .XX± 0.20 | .XX°± 1 ° |

KINGCONN 皇海科技股份有限公司

名稱(TITLE): SD PUSH H:2.7

| 單位(UNIT) | 料號(PART NO.) | 圖號(DWG NO.) |
|---|---|---|
| mm | 7SDCN-F0-0037 | 7SDCN-F0-0037 |

| 審核(APPROVAL) | 核對(CHECKED) | 製圖(DRAWN) | 比例 SCALE 1:1 | 張數 SHEET 1 / 1 |
|---|---|---|---|---|
| | | | 專案 PROJ. | 更改 REV A |

RoHS